



Product Change Notification - LIAL-04CMGK362

Date:

25 Mar 2020

Product Category:

Power Management - System Supervisors/Voltage Detectors; Camera Flash LED Drivers; Switching Regulators; Power Management - Power Switches; Capacitive Touch Sensors; 8-bit Microcontrollers; Temperature Sensors; Memory

Affected CPNs:**Notification subject:**

CCB 4134 Initial Notice: Qualification of JCP2 as a new bumping facility for selected products available in 4L WLCSP, 5L WLCSP, 6L WLCSP, 8L WLCSP, 9L WLCSP, 12L WLCSP and 16L WLCSP packages.

Notification text:**PCN Status:**

Initial notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of JCP2 as a new bumping facility for selected products available in 4L WLCSP, 5L WLCSP, 6L WLCSP, 8L WLCSP, 9L WLCSP, 12L WLCSP and 16L WLCSP packages.

Pre Change:

Bumping facility at JCAP

Post Change:

Bumping facility at JCP2

Pre and Post Change Summary:

	Pre Change	Post Change
Bumping facility	JIANGYIN CHANGDIAN ADVANCED PACKAGING LTD B1 Line (JCAP)	JIANGYIN CHANGDIAN ADVANCED PACKAGING LTD B2 Line (JCP2)

Impacts to Data Sheet:

None



Change Impact:

None

Reason for Change:

To improve on time delivery performance by qualifying JCP2 as a new bumping facility

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

July 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	March 2020					-->	July 2020				
	10	11	12	13	14		27	28	29	30	31
Initial PCN Issue Date				X							
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan

Revision History:

March 25, 2020: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_LIAL-04CMGK362_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.



If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

MIC2873YCS-TR
MIC2874YCS-T5
MIC2874YCS-TR
MIC23156-0YCS-TR
MIC23156-2YCS-TR
MIC94161YCS-TR
MIC94162YCS-TR
MIC94163YCS-TR
MIC94164YCS-TR
MIC94165YCS-TR
AT42QT1050-UUR
ATTINY20-UUR
AT30TS74-UFM13-T
AT30TS74-UFM10-T-072
AT30TS74-UFM11-T-072
AT30TS74-UFM12-T-072
AT30TS74-UFM13-T-072
AT30TS74-UFM14-T-072
AT30TS74-U1FMAB-T
AT30TS74-U1FMBB-T
AT30TS74-U1FMCB-T
AT30TS74-U1FMDB-T
AT30TS74-U1FMEB-T
AT30TS74-U1FMFB-T
AT30TS74-U1FMGB-T
AT30TS74-U1FMHB-T
AT24C64D-U2UM0B-T
AT24C64D-UUM0B-T
AT24C128C-UUM0B-T
AT24CM02-U1UM0B-T
AT24C08D-UUM0B-T
AT24C08D-UUM0B-T-894
AT24C16D-UUM0B-T
AT24C32E-UUM0B-T
AT21CS01-U1UM0B-F
24CW640T-I/CS0668
MIC2782CLYCS-TR
MIC2782CRYCS-TR
MIC2782DLYCS-TR
MIC2782DRYCS-TR
MIC2782ELYCS-TR
MIC2782EMYCS-TR
MIC2782FLYCS-TR
MIC2782FRYCS-TR



QUALIFICATION PLAN SUMMARY

PCN#: LIAL-04CMGK362

Date
March 18, 2020

Qualification of JCP2 as a new bumping facility for selected products available in 4L WLCSP, 5L WLCSP, 6L WLCSP, 8L WLCSP, 9L WLCSP, 12L WLCSP and 16L WLCSP packages.

Purpose: Qualification of JCP2 as a new bumping facility for selected products available in 4L WLCSP, 5L WLCSP, 6L WLCSP, 8L WLCSP, 9L WLCSP, 12L WLCSP and 16L WLCSP packages.

Package/Die Data:

Assembly site	JCAP B2
BD number	D-004250
CCB	4134
Qual rev	C
MPN	TKKA1TFBAA04
CPN	MIC2782DRYCS-TR
Mask	TKKA1
Package Group	WLCSP
Pin count	6
PI material	PI
UBM composition	Ti/Cu/Cu
UBM size	230 um
Ball size	250 um
Ball pitch	0.4 mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot	# of CSP Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Required/Info	Special Instructions	Test Format
Temp Cycle	-40°C to 125°C for 1000 cycles. Electrical test pre and post stress at +25°C (required).	77 units*	5	3	82	0	15	Required	Spares should be properly identified.	CSP Board Level Data